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Jul 23, 1980

DERWENT-ACC-NO: 1980-66161C

DERWENT-WEEK: 198038

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TITLE: Two-component epoxy! resin adhesive contg. filler - with poly-amine adduct of
of bisphenol=A resin and epoxy-silane as hardener

INVENTOR: BRAUN, W; SOMMER, H J

PRIORITY-DATA: 1979DD-0212363 (April 20, 1979)

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PATENT-FAMILY:

PUB-NO	PUB-DATE	LANGUAGE	PAGES	MAIN-IPC
<input type="checkbox"/> <u>DD 142964 A</u>	July 23, 1980		000	
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INT-CL (IPC): C09J 3/16

ABSTRACTED-PUB-NO: DD 142964A

BASIC-ABSTRACT:

In the prepn. of a filled, two-component epoxy resin adhesive, there is added to the the resin a hardener consisting of an adduct, contg. a filler, of (a) an aliphatic polyamine on (b) a low-mol. bisphenol A epoxy resin with epoxy equiv. wt. of 200 and and a silane tackifier contg. epoxy gps. The adduct is prepd. by reacting (a) 2-3x the amine equiv. wt. of an aliphatic polyamine, with (b) a mixt. of 1 epoxy equiv. wt. of the bisphenol A epoxy resin, and the silane tackifier, at 70-80 degrees C.

The adhesive is used to bond non-porous and non-absorbent building materials, e.g. metal and glass. The process is cheap and insolves little manual labour. The adhesive is resistant to aq. media. The amt. of silane used is small.

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